PCN Number:	20240221013.1	**PCN Date:**	February 22, 2024
Title:	Qualification of TIPI as an additional Assembly site for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	May 22, 2024	**Sample Requests accepted until:**	$CRF_SamplesAcceptedUntil$*

March 23, 2024 will not be supported.

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of TIPI as an additional Assembly site for set of devices listed below. Construction differences are as follows:

	AP3	TIPI
Wire type/diam	0.8mil Au	0.8mil Cu
Mount Compound	101375377	4205412
Mold Compound	101342201	4206745

Reason for Change:

Supply continuity

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
AMKOR P3	AP3	PHL	Binan
TI Philippines	PHI	PHL	Baguio City

Sample product shipping label (not actual product label)

Product Affected:

AFE5828ZAV	AFE58JD28ZAV

Qualification Report

Approve Date 23-January-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: AFE5828ZAV
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0
FTY	E6	Final Test Yield	-	-	3/3/0

QBS: Qual By Similarity
Qual Device AFE5828ZAV is qualified at MSL3 260C
Qual Device AFE5828ZAV is qualified at MSL3 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.